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RESPONSE UNDER 37 CFR 1.116
EXPEDITED PROCEDURE
EXAMINING GROUP 2822PATENT APPLICATION
Docket No.: 9903-071
Client Ref. No.: S02US035

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Jin-Hyuk LEE, et al.

Serial No.:	10/690,782	Examiner:	Graybill, David E.
Filed:	October 21, 2003	Group Art Unit:	2822
Confirmation No.:	5611		
For:	METHOD FOR MANUFACTURING A WAFER LEVEL CHIP SCALE PACKAGE		

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Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR 1.116

Responsive to the Final Office Action, Paper No. 20051119, dated November 23, 2005, please amend the application as follows.

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 6 of this paper.

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